



Material Content Data Sheet



Sales Product Name	TLE5011			Issued	20. July 2018			
MA#	MA000983744							
Package	PG-DSO-8-16			Weight*	83.41 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.837	3.40	3.40	34007	34007
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8598	
wire	non noble metal	copper	7440-50-8	29.121	34.91	35.82	349128	358263
	noble metal	gold	7440-57-5	0.173	0.21	0.21	2080	2080
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1143
encapsulation	plastics	epoxy resin	-	4.386	5.26		52581	
	inorganic material	silicondioxide	60676-86-0	43.191	51.79	57.16	517813	571537
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9757	9757
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7796	7796
glue	plastics	acrylic resin	-	0.304	0.36		3643	
	noble metal	silver	7440-22-4	1.077	1.29	1.65	12917	16560
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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